

PRODUCT SPECIFICATION

SPEC. NO: C-2604-03

DATE: Apr.1,2026

CUSTOMER'S PRODUCT NAME:

EMTEK PRODUCT NAME:

BCMF060503900M00

THIS SPECIFICATION IS:

- ☐ FULLY ACCEPTED
- ☐ DENIED
- ☐ ACCEPTED UNDER THE FOLLOWING CONDITIONS



SIGNATURE: _____ DATE: _____

NAME(PRINT): _____

TITLE: _____

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EMTEK CO., LTD.

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1. Features

- Effective for suppressing common mode noise and almost no effect for high speed differential data line.
- Ultra low profile (0.64x0.57x0.35mm).
- Ceramic multilayer type SMD component.
- Non-polarized product.
- It is a product conforming to RoHS directive.

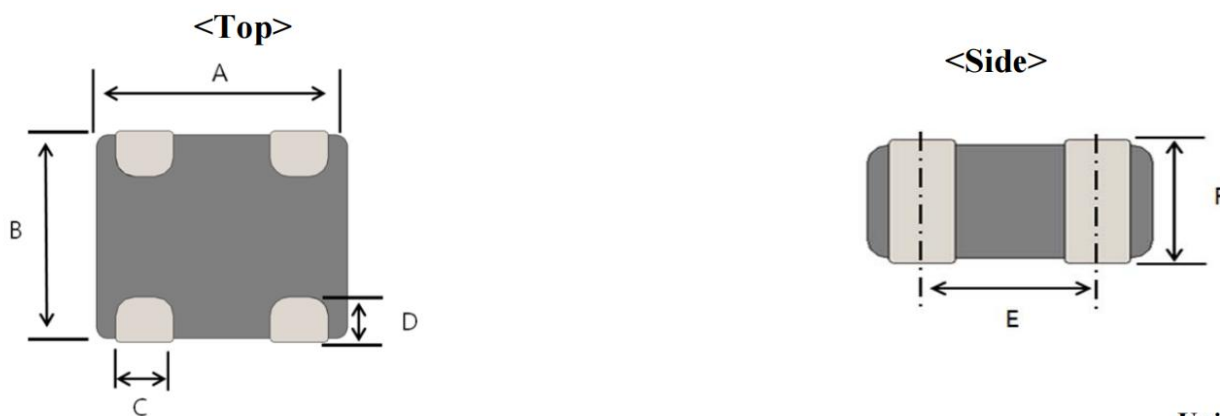
2. Application

- HDMI lines in PDP, LCD TV, DVD Player, PC, Audio player, DSC.
- MDDI, MIPI in mobile phone.

3. Part numbering

B	-	CMF	-	060503	-	900	-	M	-	00
Grade		Product Series		Dimensions(mm)		Impedance (Ω)		Tolerance		Control code

4. Appearance and Dimensions



Unit : mm

Item	A	B	C	D	E	F
Size(mm)	0.64±0.05	0.57±0.05	0.15±0.05	0.15±0.05	0.4±0.1	0.35±0.03

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5. Rating

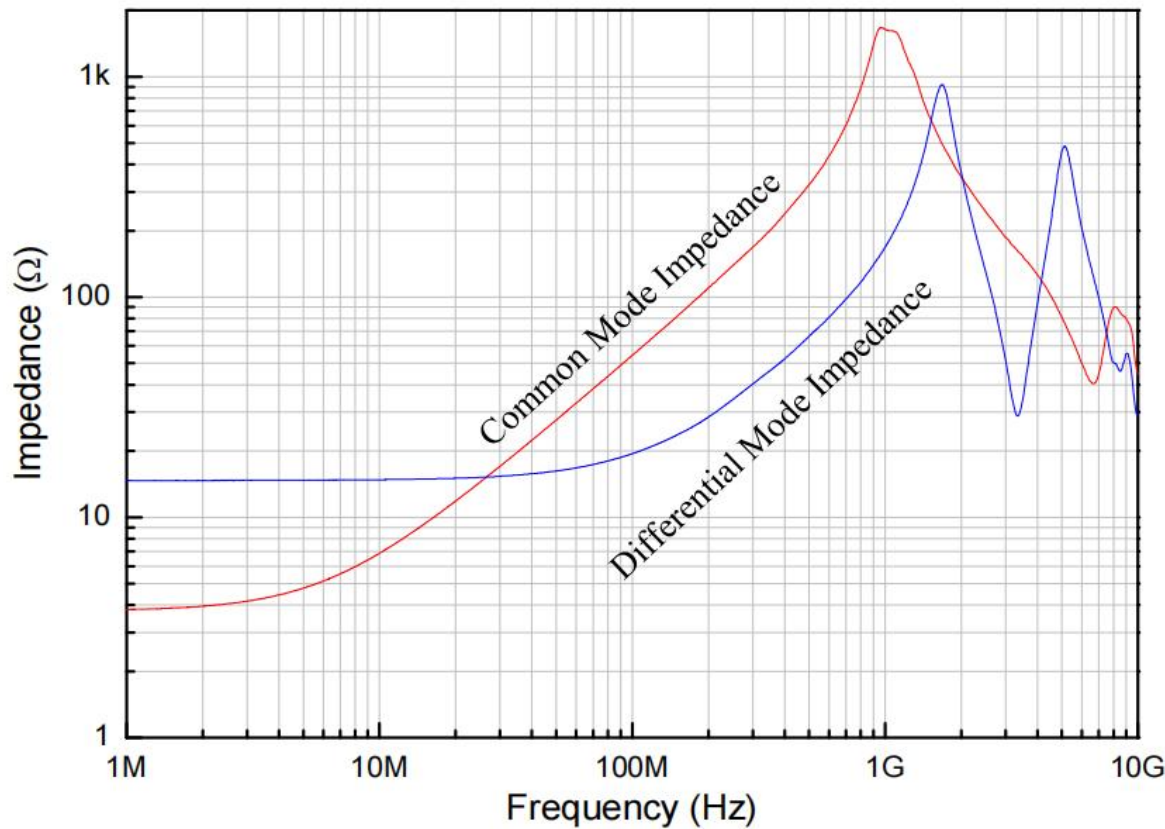
NOTE:

- Operating temperature: -40°C ~ + 85°C

ELECTRICAL CHARACTERISTICS

Part No.	Impedance (Ω)	Test Freq	DCR (Ω)	Rated Current (mA)	Rated Voltage (V) Dc	Insulation Resistance (MΩ)
BCMF060503900M00	90 (±25%)	100MHz	Max 10	Max 50	5	Min 10

Typical Eleectrical Characteristics

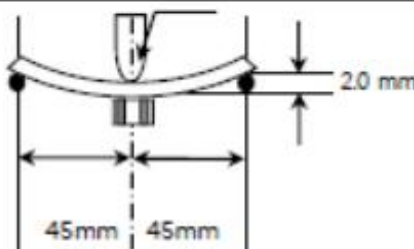
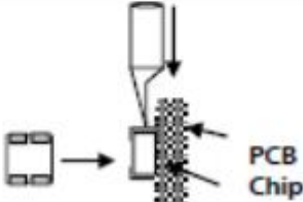


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6. Reliable Performance

No	ITEM	REQUIREMENT	TEST CONDITION
1	Reflow soldering	No mechanical damage. More than 50% of the terminal Electrode shall be covered with new solder.	-Pre-heating temperature : 160 ~ 185°C time : 110 ±10 sec -Soldering temperature : over 220°C time : 40 ±10 sec -Peak temperature : max 260°C time : max 10sec.
2	Bending Strength test	No mechanical damage. impedance change: within ±30%	
3	Adhesive strength of Terminal electrode	Adhesion strength should be over 0.5kgf	
4	Thermal shock	No mechanical damage. impedance change: within ±30%	Step 1: -40 ±2°C 30 ±3min. Step 2: 85 ±2°C 30 ±3min. Number of cycle : 100 times Then measured after exposure in the room condition for 24±2hrs
5	Heat Load resistance	No mechanical damage. impedance change: within ±30%	Temperature : 85 ±2°C Bias : Rated Current Time: 168hrs Then measured after exposure in the room condition for 24±2hrs
6	Humidity load resistance	No mechanical damage. impedance change: within ±30%	Temperature : 40 ±2°C Humidity : 90 ~ 95%RH Bias : Rated Current Time: 168hrs Then measured after exposure in the room condition for 24±2hrs
7	Low Temp. resistance	No mechanical damage. impedance change: within ±30%	Temperature : -40 ±2°C Time: 168hrs Then measured after exposure in the room condition for 24±2hrs



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- Result

No	ITEM	REQUIREMENT	Sample Size	Ac, Re	Result
1	Reflow soldering	No mechanical damage. More than 50% of the terminal Electrode shall be covered with new solder.	10	0,1	OK
2	Bending Strength test.	No mechanical damage. impedance change: within $\pm 30\%$	10	0,1	OK
3	Adhesive strength of Terminal electrode	Adhesion strength should be over 0.5kgf	10	0,1	OK
4	Thermal shock	No mechanical damage. impedance change: within $\pm 30\%$	10	0,1	OK
5	Heat Load resistance	No mechanical damage. impedance change: within $\pm 30\%$	10	0,1	OK
6	Humidity Load resistance	No mechanical damage. impedance change: within $\pm 30\%$	10	0,1	OK
7	Low Temp. resistance	No mechanical damage. impedance change: within $\pm 30\%$	10	0,1	OK



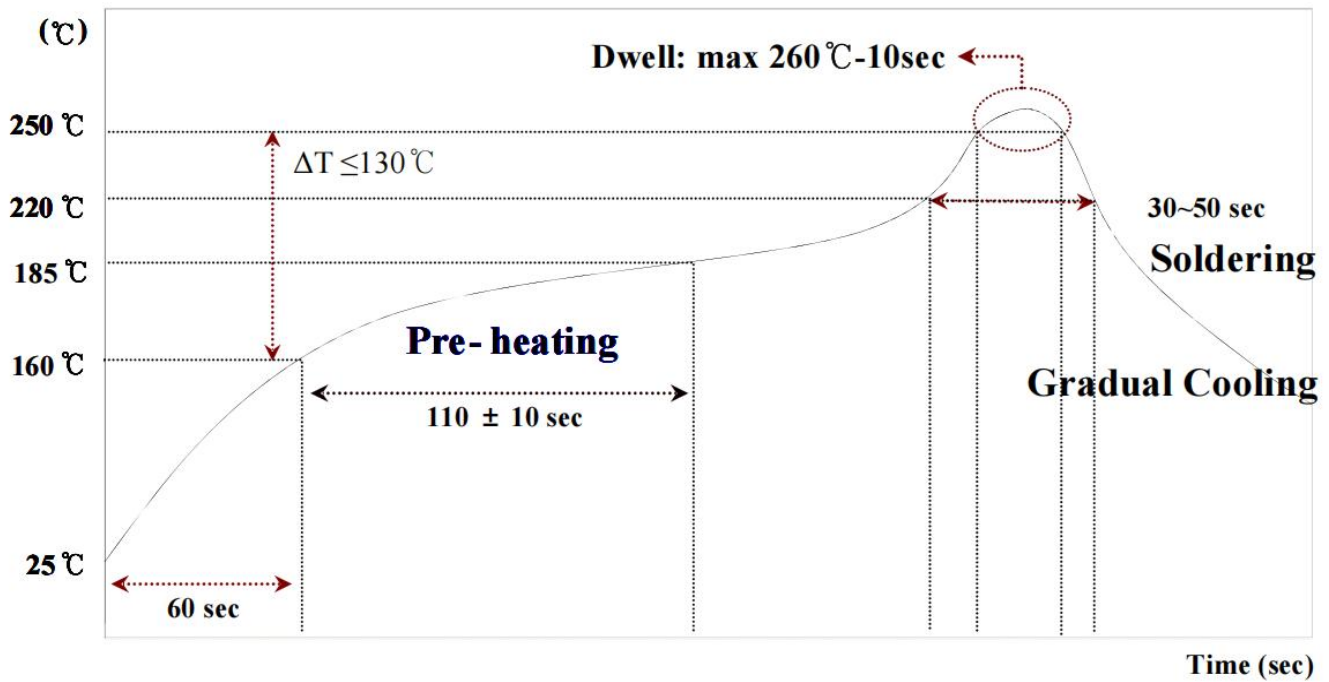
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7.Recommended Soldering Conditions

7.1 RECOMMENDED SOLDERING PROFILE (Lead-free condition)



7.2 RECOMMENDED LEAD-FREE SOLDER PASTE

- Supplier : Tamura Donghwa
- Main composition : Sn-Ag-Cu
- Ratio of composition : 96.5%-3.0%-0.5%

7.3 RECOMMENDED HAND SOLDER

- Max Temperature: Max 380 °C(Max 5sec)

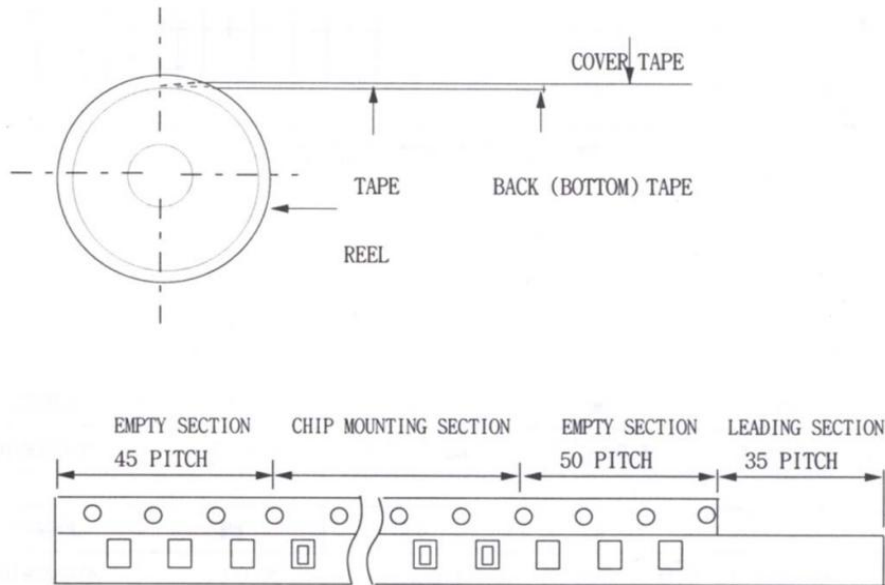
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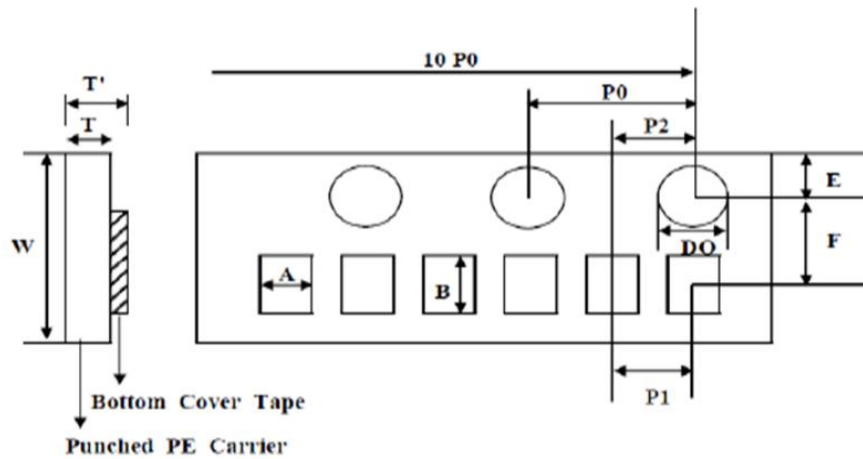
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8. Packaging

8.1 TAPING FIGURE



8.2 CARRIER TAPE DIMENSIONS



Unit : mm

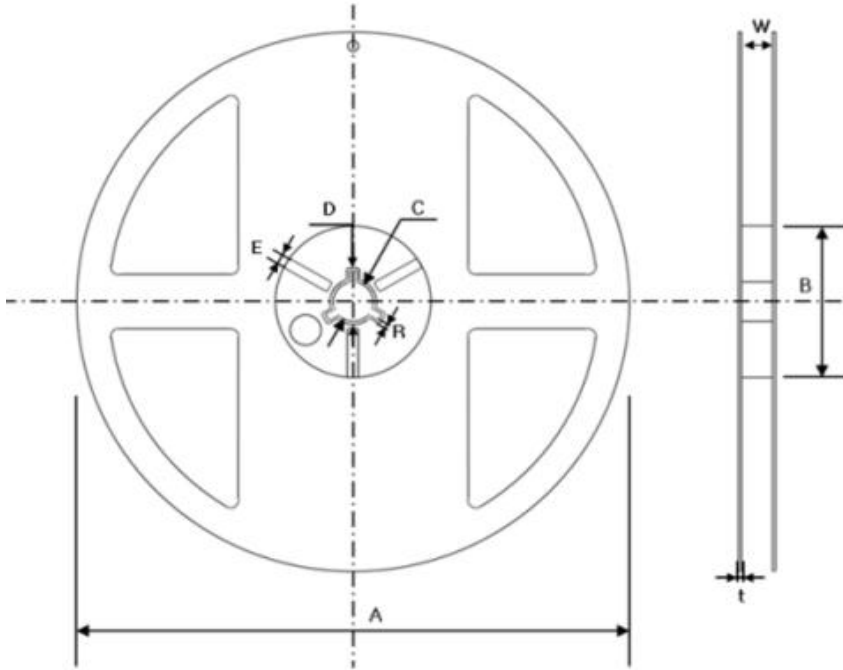
SYMBOL	A	B	E	F	D0	P1	P2	P0	10P0	W	T	T'
DIMENSION	0.62	0.78	1.75	3.50	1.55	2.00	2.00	4.00	40.00	8.00	0.40	0.43
TOLERANCE	±0.03	±0.03	±0.05	±0.05	±0.03	±0.05	±0.05	±0.05	±0.10	±0.10	±0.02	±0.05

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8.3 REEL DIMENSIONS



(1) Reel Materials: Polystyrene

(2) Label

CODE	A	B	C	D	E	W	t	R
DIMENSION	$\phi 178 \pm 2$	Min. $\phi 50$	$\phi 13 \pm 0.5$	$\phi 20 \pm 0.8$	3.0 ± 0.5	10 ± 1.5	1.3 ± 0.2	1.0 ± 0.2

8.4 Packaging quantities

- Standard Packing Quantity per Reel ($\Phi 178$)

- Paper Tape: 10,000pcs

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9.Storage

(1) Storage period

Use the products within 24 months after delivered. Solderability should be checked if this period is exceeded.

(2) Storage conditions

●Storage temperature: 20~25℃

●Storage environment: 20~25℃ humidity: RH40%~60%

(3) Delivery

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

**EMTEK CO., LTD.**